ABSTRACT

At least two electric elements (203) such as semiconductor chips or surface acoustic wave devices are mounted on wiring patterns (201), and the electric elements (203) are sealed with a thermosetting resin composition (204). An upper surface of the at least two electric elements (203) and an upper surface of the thermosetting resin composition (204) are abraded at the same time, thereby forming surfaces substantially flush with each other. Since they are abraded while being sealed with the thermosetting resin composition (204), it is possible to reduce the thickness without damaging the electric elements (203). Also, the electric elements (203) and the wiring patterns (201) can be prevented from being contaminated by an abrasive liquid. In this manner, it is possible to obtain an electric element built–in module whose thickness can be reduced while maintaining its mechanical strength.